

120V N-Channel Enhancement Mode MOSFET

Description

The AP200N12P/T uses advanced **SGT_r** technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 120V$ (Type: **135V**) $I_D = 200A$

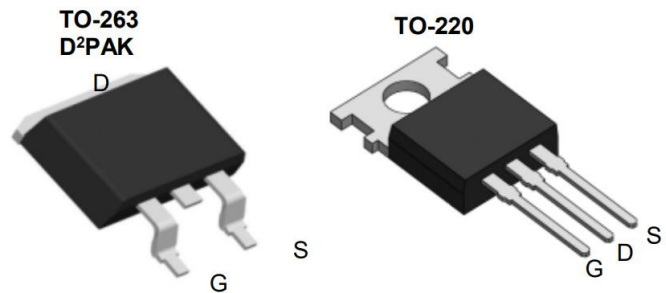
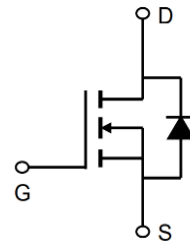
$R_{DS(ON)} < 4.2m\Omega @ V_{GS}=10V$ (Type: **3.7mΩ**)

Application

BMS

UPS

Power Management Switches



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP200N12P	TO-220-3L	AP200N12P XXX YYYY	1000
AP200N12T	TO-263-3L	AP200N12T XXX YYYY	800

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	120	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	200	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	150	A
IDM	Pulsed Drain Current	600	A
EAS	Single Pulse Avalanche Energy	530	mJ
IAS	Avalanche Current	45	A
$P_D @ T_C=25^\circ C$	Total Power Dissipation ⁴	240	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	0.75	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	62	$^\circ C/W$



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Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Type	Max.	Unit
VDSS	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	120	135	-	V
IGSS	Gate-body Leakage current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
IDSS	Zero Gate Voltage Drain Current T _J =25°C	V _{DS} = 120V, V _{GS} = 0V	-	-	1	μA
IDSS	Zero Gate Voltage Drain Current T _J =100°C		-	-	100	
VGS(th)	Gate-Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0	2.9	4.0	V
RDS(on)	Drain-Source on-Resistance ²	V _{GS} = 10V, I _D = 20A	-	3.7	4.2	mΩ
RDS(on)	Drain-Source on-Resistance ²	V _{GS} = 6V, I _D = 20A	-	4.3	5.8	mΩ
Ciss	Input Capacitance	V _{GS} = 0V, V _{DS} = 60V, f = 250kHz	-	5240	-	pF
Coss	Output Capacitance		-	739	-	
Crss	Reverse Transfer Capacitance		-	12	-	
R _g	Gate Resistance	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	-	1.7	-	Ω
Q _g	Total Gate Charge	V _{DD} = 60V, I _D = 45A, V _{GS} = 0 to 10V	-	19	-	nC
Q _{gs}	Gate-Source Charge		-	11	-	
Q _{gd}	Gate-Drain Charge		-	75	-	
td(on)	Turn-on Delay Time	V _{DD} = 60V, V _{GS} = 10V, I _D = 45A, R _G = 10Ω	-	59	-	ns
t _r	Rise Time		-	41	-	
td(off)	Turn-off Delay Time		-	96	-	
t _f	Fall Time		-	33	-	
VSD	Diode Forward Voltage ²	I _F = 20A, V _{GS} = 0V	-	0.8	1.2	V
I _S	Continuous Source Current ^{1,5}	V _G = V _D = 0V, Force Current	-	-	200	A
trr	Body Diode Reverse Recovery Time	V _R = 60V I _F = 35A, di/dt = 100A/μs	-	70	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	200	-	nC

Notes:

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is V_{DD}=50V, V_{GS}=10V, L=0.5mH, I_{AS}=45A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

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Typical Characteristics

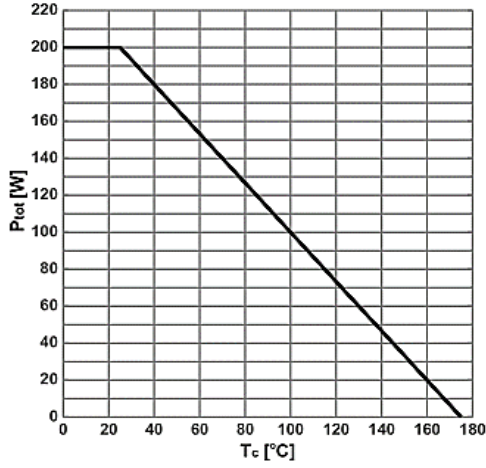


Figure 1. Power dissipation

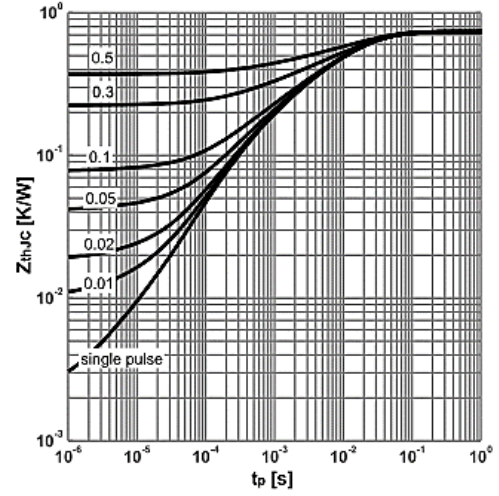


Figure 2. Max. transient thermal impedance

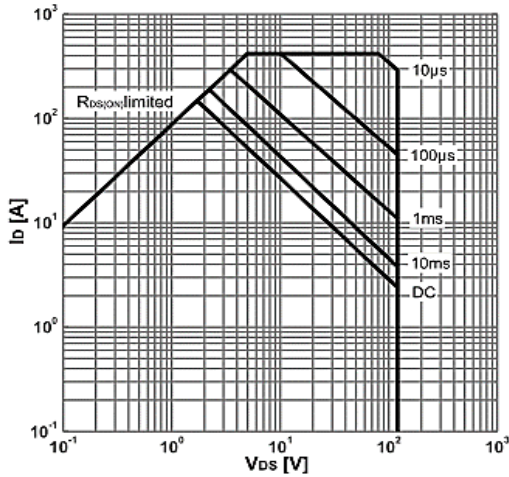


Figure 3. Safe operating area

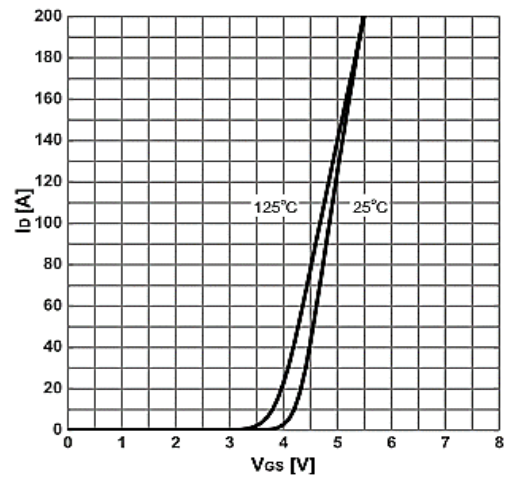


Figure 4. Iype. transfer characteristics

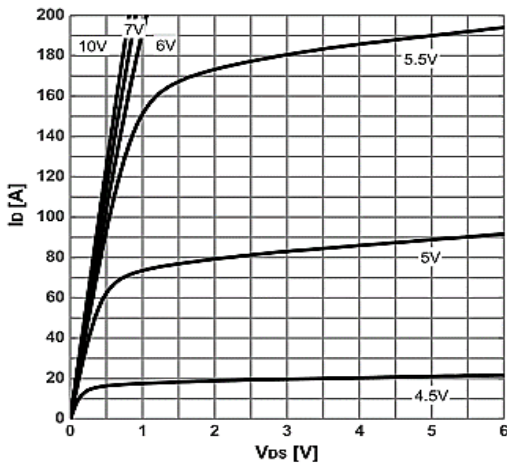


Figure 5. Typ. output characteristics(Tj 25°C)

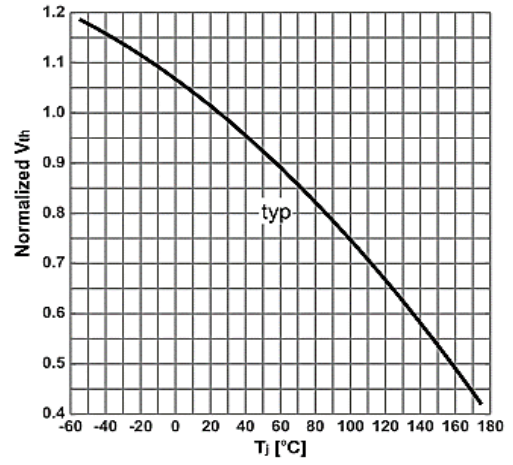


Figure 6. Typ. output characteristics(Tj 125°C)

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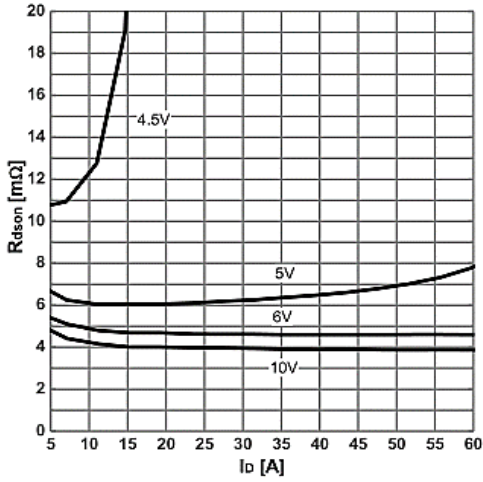


Figure 7. On-state resistance vs. Drain current

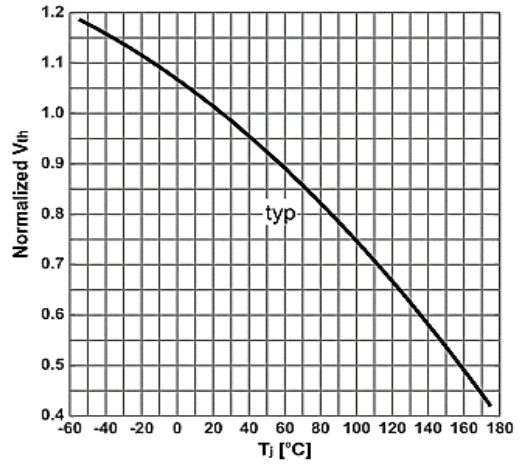


Figure 6. Gate threshold voltage vs. Junction Temperature

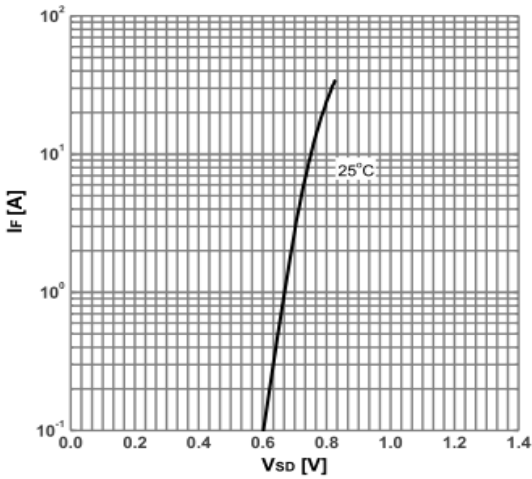


Figure 9. Forward characteristics of reverse diode

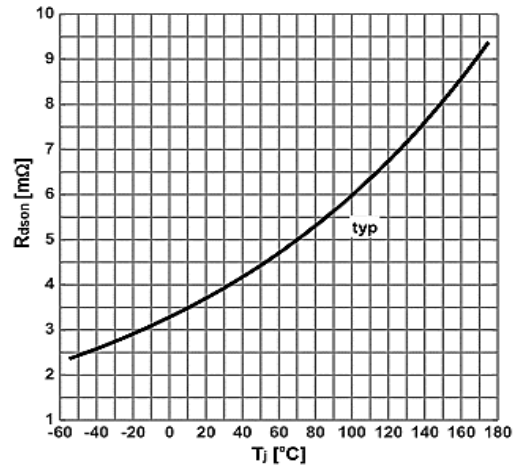


Figure 8. On-state resistance vs. Junction temperature

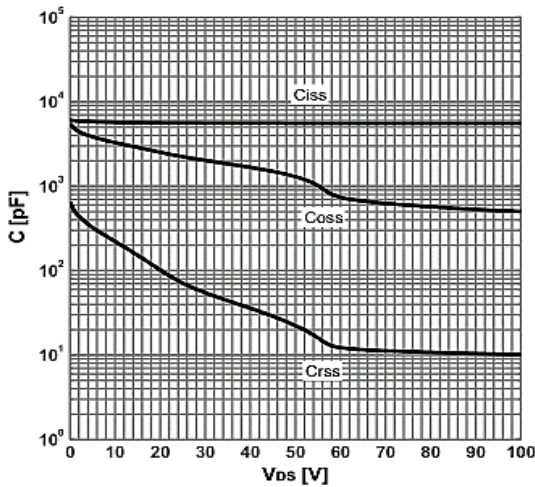


Figure9 Typ. capacitances

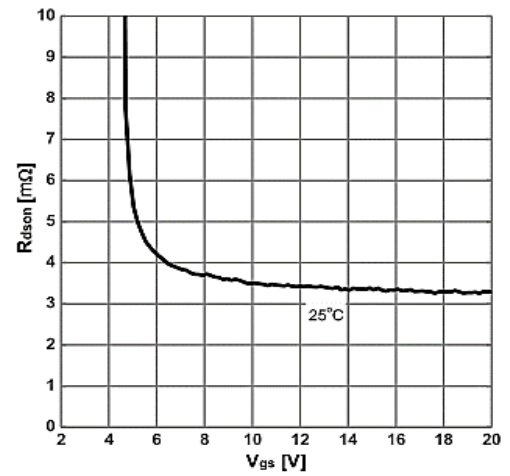


Figure11. On-state resistance vs. Vgs characteristics

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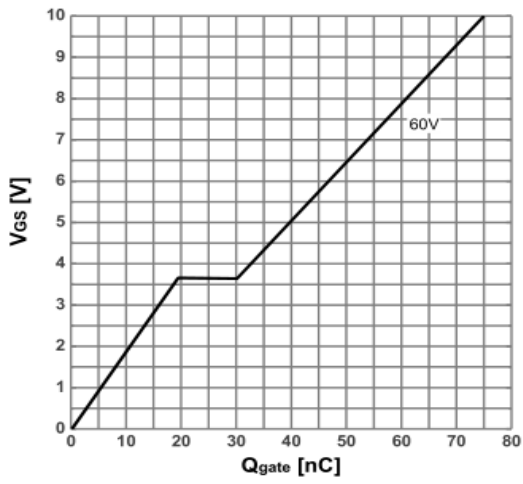
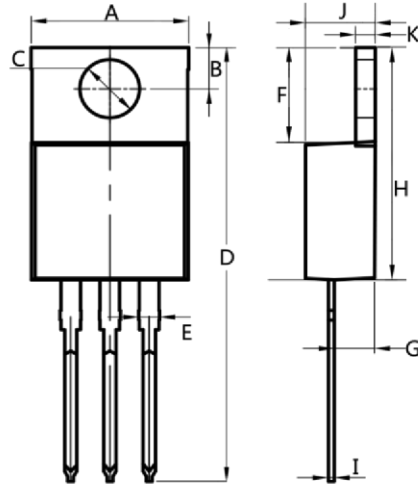


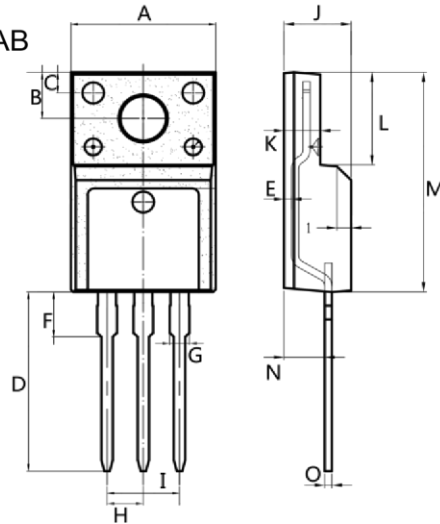
Figure 13: Typ. gate charge

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TO-220AB


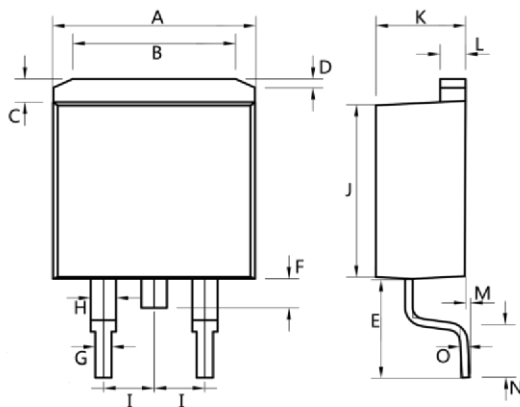
Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter

ITO-220AB


Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60

All Dimensions in millimeter

TO-263


Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter